## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Young Hoon PARK, et al.	)
Serial No.:	10/511,883	) Group Art Unit: 1763
Filed:	October 19, 2004	) ) Examiner: ) NG, James Wai Heung ) )
For:	APPARATUS AND METHOD FOR DEPOSITING THIN FILM ON WAFER USING REMOTE PLASMA	

## REPLY TO FINAL OFFICE ACTION UNDER 37 CFR 1.114 WITH REQUEST FOR CONTINUED EXAMINATION

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action mailed September 11, 2007, Applicants request reconsideration in view of the following amendments and remarks for entry in the above-identified application.

Amendments to the Claims begin on page 2 of this paper; and

Remarks begin on page 7 of this paper.